

2827
jw

Atty. Dkt. No: AMK-11443



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Lee John Smith et al.
 Application No.: 09/944,732 Art Unit.: 2827
 Filing Date: 08/31/2001 Examiner: David Graybill
 For: "THIN SEMICONDUCTOR PACKAGE INCLUDING STACKED DIES"

Mail Stop Non-Fee Amendment
 Commissioner for Patents
 P.O. Box 1450
 Alexandria, VA 22313-1450

Date: June 1, 2004

AMENDMENT TRANSMITTAL

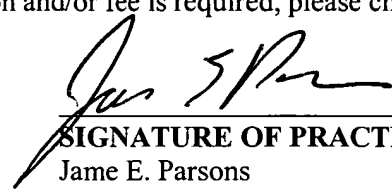
1. Transmitted herewith is an amendment for this application.
2. **STATUS:** Applicant is other than a small entity.
3. **EXTENSION OF TERM:** The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply. Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.
4. **FEE FOR CLAIMS:** The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

	(Col.1)		(Col. 2)	(Col. 3)	LARGE ENTITY	
	Claims Remaining After Amendment		Highest No. Previously Paid For	Present Extra	Rate	Addit. Fee
Total	9	Minus	25	= 0	x \$18 =	\$0
Indep.	1	Minus	5	= 0	x \$86 =	\$0
First Presentation of Multiple Dependent Claim					+ \$290 =	\$0
Total					Addit. Fee	\$0

No additional fee for claims is required.

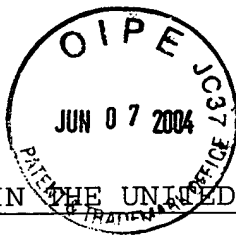
5. **FEE DEFICIENCY:** If any additional extension and/or fee is required, please charge Deposit Account No. 50-0574.

Customer No. 022888
 Tel.: (408) 451-5906


SIGNATURE OF PRACTITIONER
 Jame E. Parsons
 Reg. No. 34,691

I hereby certify that this correspondence is being deposited with the United States Postal Service as FIRST CLASS MAIL in an envelope addressed to: Mail Stop Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on June 1, 2004.

Date: 6/1/2004 Signature: Rebecca A. Baumann
 Date: Signature: Rebecca A. Baumann



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Lee John Smith et al.
Assignee: Amkor Technology, Inc.
Title: Thin Semiconductor Package Including Stacked Dies
Serial No.: 09/944,732-2003 File Date: 8/31/01
Examiner: Graybill, David Art Unit: 2827
Docket No.: AMK-11443

Date: June 1, 2004

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AMENDMENT IN RESPONSE TO THE OFFICE ACTION OF 3/3/04

Dear Sir:

In response to the first Office Action mailed from the Patent Office on March 3, 2004, please amend the application as follows.